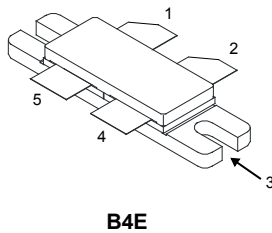


400 W, 50 V, 0.4 to 1 GHz RF power LDMOS transistor



Pin connection	
Pin	Connection
1	Drain A
2	Drain B
3	Source (bottom side)
4	Gate B
5	Gate A

Features

Order code	Frequency	V _{DD}	P _{OUT}	Gain	Efficiency
RF5L08350CB4	860 MHz	50 V	400 W	19 dB	61%

- High efficiency and linear gain operations
- Integrated ESD protection
- Internally matched for ease of use
- Large positive and negative gate-source voltage range for improved class C operation
- Excellent thermal stability, low HCI drift
- In compliance with the European Directive 2002/95/EC

Applications

- Wideband lab amplifier from 0.4 to 1 GHz
- Digital UHF TV 470-860 MHz
- 650 MHz particle accelerator
- 915 MHz RF energy applications

Description

The **RF5L08350CB4** is a 400 W, 50 V high-performance, internally matched LDMOS FET, designed for multiple applications over the frequency band 0.4 to 1 GHz.



Product status link
RF5L08350CB4

Product summary	
Order code	RF5L08350CB4
Marking	5L08350
Package	B4E
Packing	Tape and reel 13"
Base/bulk quantity	120/120

1 Electrical ratings

Table 1. Absolute maximum ratings ($T_C = 25\text{ °C}$)

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	110	V
V_{GS}	Gate-source voltage	-8 to 10	V
V_{DD}	Maximum operating voltage	55	V
T_{STG}	Storage temperature range	-65 to +150	°C
T_J	Maximum junction temperature	200	°C

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thJC}^{(1)}$	Thermal resistance, junction-to-case	0.35	°C/W

1. $T_C = 85\text{ °C}$, $T_J = 200\text{ °C}$, DC test.

Table 3. ESD protection

Symbol	Test methodology	Class
HBM	Human body model (according to ANSI/ESDA/JEDEC JS001-2017)	2
CDM	Charge device model (according to ANSI/ESDA/JEDEC JS-002-2014)	C3

2 Electrical characteristics

$T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified.

Table 4. Static (per side)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	110	-		V
I_{DSS}	Zero-gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 50\text{ V}$		-	1	μA
		$V_{DS} = 0\text{ V}, V_{GS} = 90\text{ V}$		-		
I_{GSS}	Gate-body leakage current	$V_{GS} = -8/10\text{ V}, V_{DS} = 0\text{ V}$		-	± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = 50\text{ V}, I_D = 600\text{ }\mu\text{A}$	1	-	3	V
$V_{GS(Q)}$	Gate quiescent voltage	$V_{DS} = 1\text{ V}, I_D = 100\text{ mA}$	2	-	5	V
$V_{DS(on)}$	Static drain-source on-voltage	$V_{GS} = 10\text{ V}, I_D = 5\text{ A}$		-	1.4	V
$R_{DS(on)}$	Drain-source on-state resistance	$V_{GS} = 10\text{ V}, V_{DS} = 100\text{ mV}$		-	1	Ω
$I_{DS(on)}$	Static drain-source on-current			-	2.5	A

Table 5. Dynamic

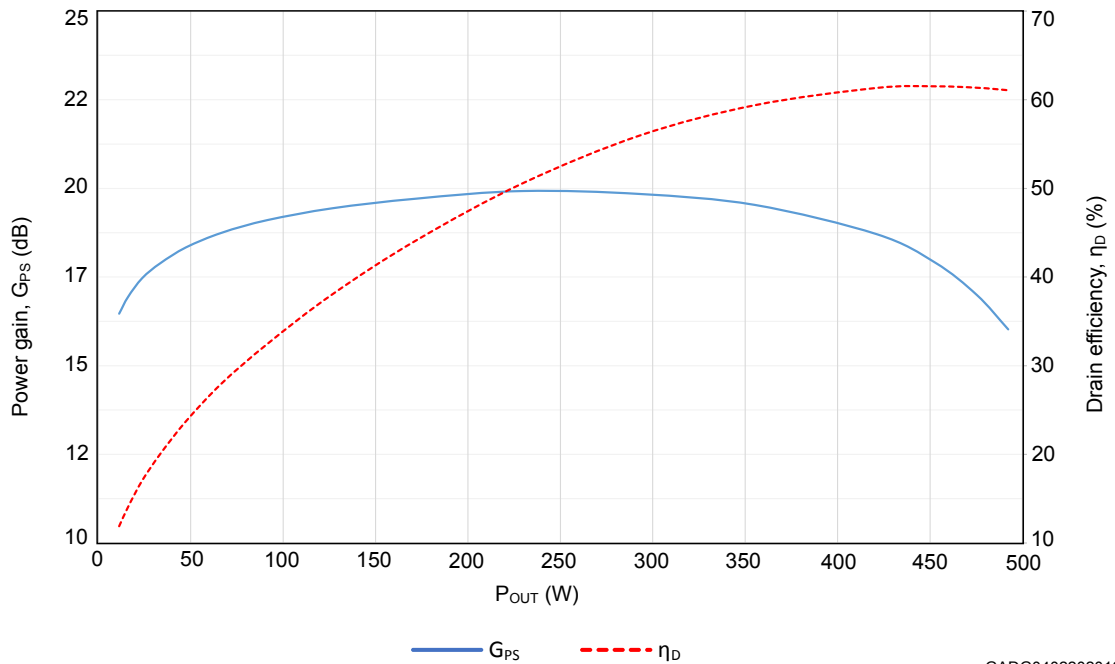
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
f	Frequency		400		1000	MHz
P_{OUT}	Output power	f = 860 MHz at 1dB compression		400		W
G_{PS}	Power gain			19		dB
η_D	Drain efficiency			61		%
VSWR	Load mismatch	$P_{OUT} = 400\text{ W}$ pulsed CW output power, all phases			10:1	

Note: $V_{DD} = 50\text{ V}, I_{DQ} = 200\text{ mA}$, pulsed CW, pulse width=100 μs , duty cycle=10%.

3 Typical performance

Table 6. Output power, power gain and drain efficiency vs input power (f = 860 MHz)

P_{IN} (dBm)	P_{OUT} (dBm)	P_{OUT} (W)	I_{DS} (A)	G_{PS} (dB)	η_D (%)
24.1	40.5	11.3	1.9	16.5	11.9
25.1	42.1	16.1	2.3	16.9	14.1
26.3	43.8	23.8	2.8	17.5	17.0
27.4	45.3	33.6	3.4	17.9	20.0
28.4	46.8	47.5	4.0	18.3	23.7
29.5	48.3	66.9	4.8	18.8	28.0
30.5	49.6	91.6	5.6	19.1	32.5
31.6	51.0	126.6	6.7	19.4	38.0
32.6	52.4	172.0	7.8	19.7	44.1
33.7	53.6	230.2	9.1	19.9	50.6
34.8	54.7	293.5	10.5	19.8	56.0
36.0	55.5	355.3	12.0	19.5	59.4
37.5	56.3	421.1	13.7	18.7	61.3
38.7	56.6	452.8	14.7	17.9	61.5
39.8	56.8	475.4	15.5	17.0	61.4
40.9	56.9	492.3	16.1	16.0	61.1

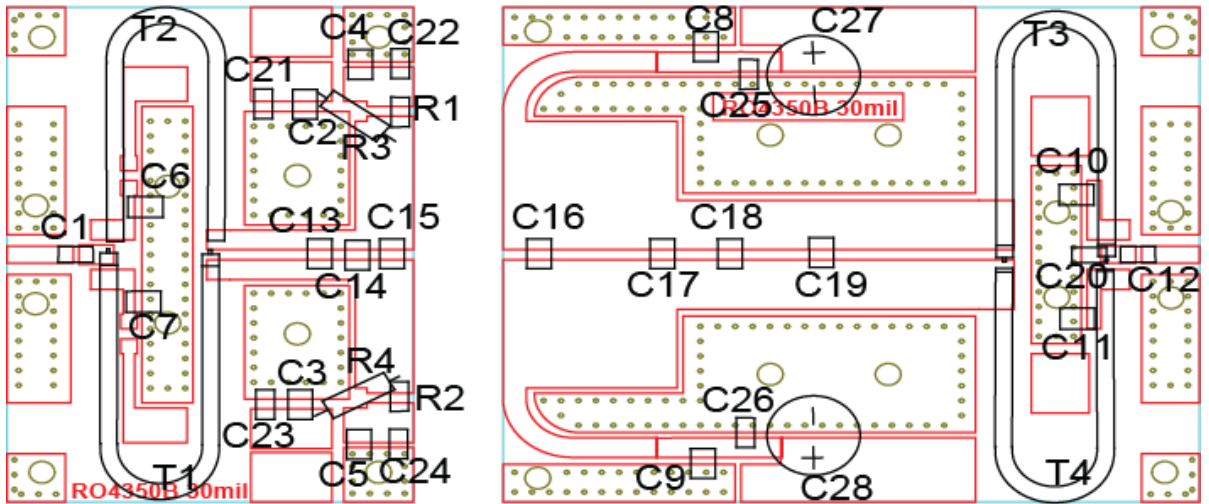
Figure 1. Power gain and efficiency vs output power (f = 860 MHz)


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Note: $V_{DD} = 50$ V, $I_{DQ} = 200$ mA, pulsed CW, pulse width = 100 μ s, duty cycle = 10%

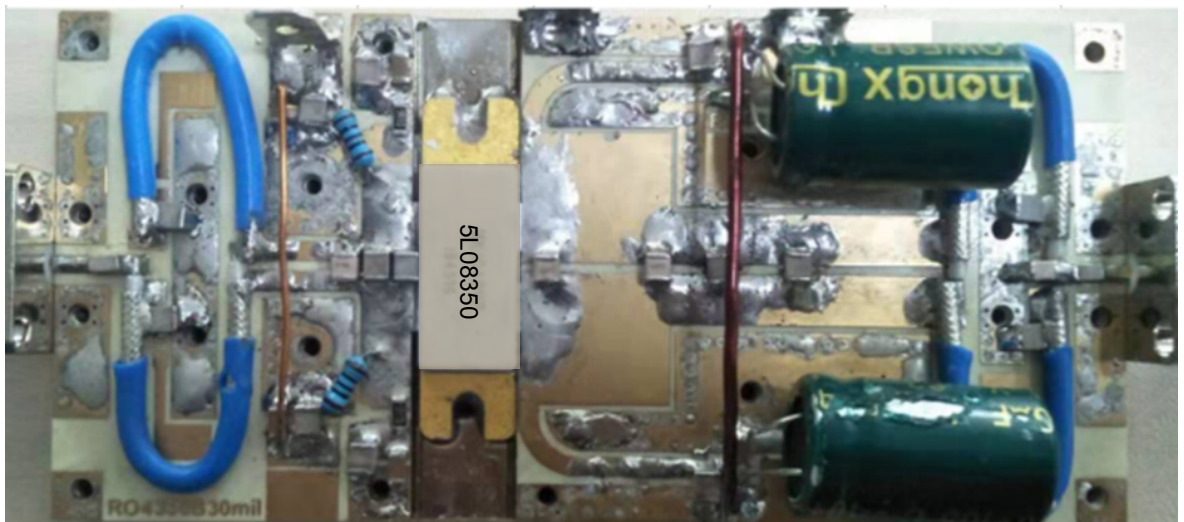
4 Test circuits

Figure 2. Test circuit layout (f = 860 MHz)



GADG040220201122SA

Figure 3. Test circuit photo (f = 860 MHz)



GADG250520201340SA

Table 7. Component list (f = 860 MHz)

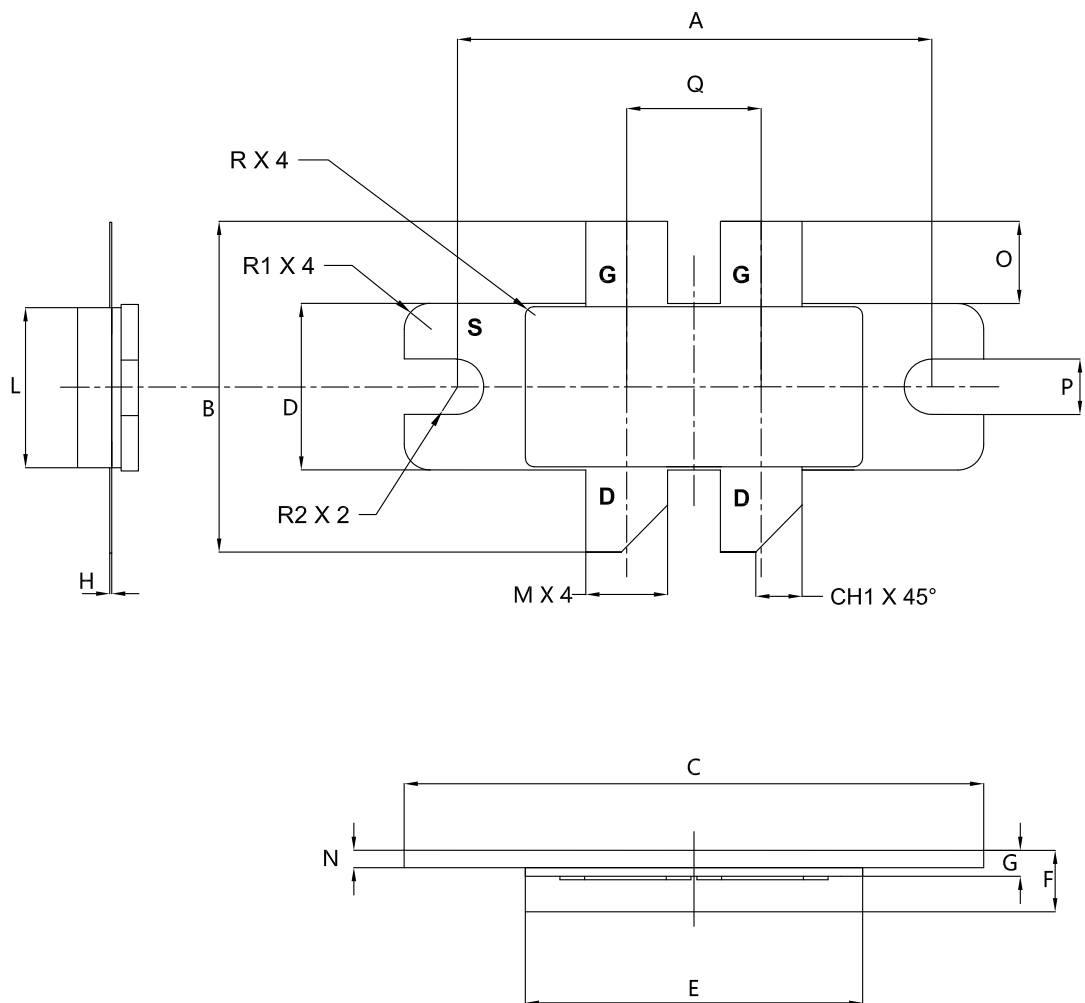
Component	Description	Reference
C1, C12	47 pF	ATC800B
C13	1.5 pF	DLC70B
C14, C19	6.8 pF	ATC800B
C15	10 pF	ATC800B
C16, C17, C20	2.2 pF	DLC70B
C18	4.7 pF	ATC800B
C21, C26	10 μ F, 100 V	
C27, C28	470 μ F, 63 V	
R1, R2	9.1 Ω	1206
R3, R4	100 Ω , 1 W	
T1, T2, T3, T4	25 Ω , 50 mm	SF-086-25

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

5.1 B4E package information

Figure 4. B4E package outline



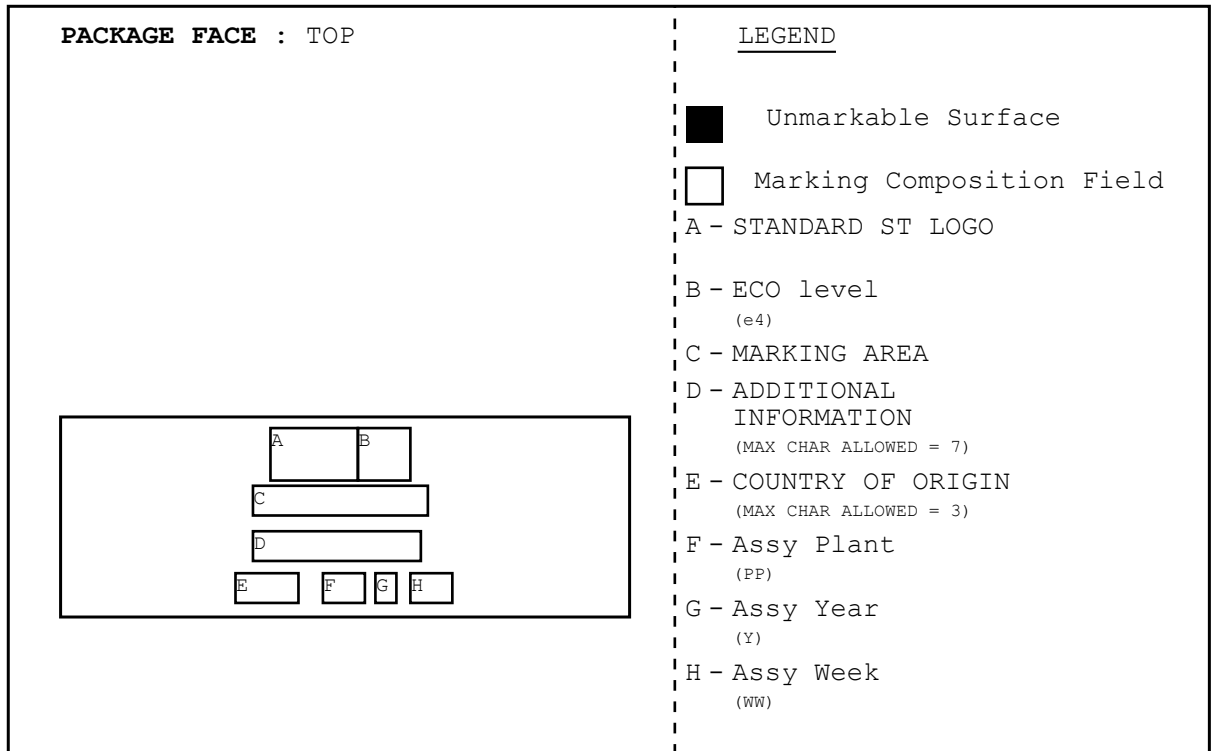
DM00418520_2

Table 8. B4E package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	27.81	27.94	28.07
B	18.93	19.43	19.93
C	33.91	34.04	34.17
D	9.65	9.78	9.91
E	19.56	19.81	20.06
F	3.23	3.61	3.99
G	1.40	1.53	1.66
H	0.07		0.15
L	9.20	9.40	9.60
M	4.67	4.80	4.93
N	0.89	1.02	1.15
O	4.70	4.83	4.96
P	3.13	3.26	3.39
Q	7.77	7.90	8.03
R		0.50	
R1		1.52	
R2		1.63	
CH1		2.72	

5.2 Marking information

Figure 5. Marking composition



GADG040220211644GT

Revision history

Table 9. Document revision history

Date	Revision	Changes
25-May-2020	1	First release.
28-Sep-2021	2	Modified features and marking on cover page Modified Table 1. Absolute maximum ratings ($T_C = 25\text{ }^\circ\text{C}$), Table 3. ESD protection, Table 4. Static (per side), Table 5. Dynamic, Figure 1. Power gain and efficiency vs output power ($f = 860\text{ MHz}$) and Figure 3. Test circuit photo ($f = 860\text{ MHz}$). Added Section 5.2 Marking information. Minor text changes.

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